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(54) POSITIVE RESIST COMPOSITION FOR ELECTRON BEAM OR X-RAY

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a positive resist composition for electron beams or X-rays having high sensitivity, high resolution and excellent edge roughness of a line pattern.

SOLUTION: The positive photoresist composition contains (a) a specified compound which generates an acid when irradiated with electron beams or X-rays, (b) a resin having the residue of a compound having a lower ionization potential than p-ethylphenol in a group which is released by the action of the acid and having solubility in an alkali developing solution increased by the action of the acid and (c) a solvent.

LEGAL STATUS

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